

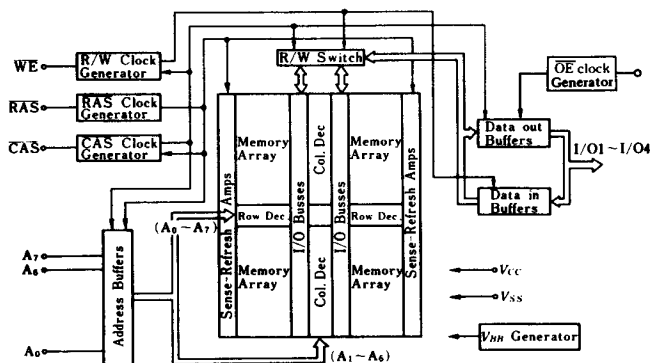
HM48416AP-12, HM48416AP-15 HM48416AP-20

16384-word × 4-bit Dynamic Random Access Memory

■ FEATURES

- 16384-word × 4-bit Organization
- Single 5V ($\pm 10\%$)
- Low Power; 303mW Active, 20mW Standby
- High speed: Access Time 120ns/150ns/200ns (max)
- Page mode capability
- Output data controlled by $\overline{\text{CAS}}$, $\overline{\text{OE}}$
- TTL compatible
- 128 refresh cycles ($A_0 \sim A_6$, 2ms)

■ BLOCK DIAGRAM



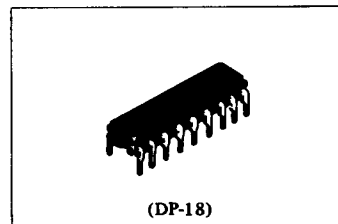
■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	-1.0 to +7.0	V
Supply Voltage relative to V_{SS}	V_{CC}	-1.0 to +7.0	V
Short Circuit Output Current	I_{out}	50	mA
Power Dissipation	P_T	1.0	W
Operating Temperature	T_{opr}	0 to +70	°C
Storage Temperature	T_{stg}	-55 to +125	°C

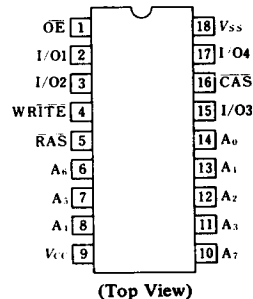
■ RECOMMENDED DC OPERATING CONDITIONS ($T_a = 0$ to +70°C)

Item	Symbol	min	typ	max	Unit
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
	V_{SS}	0	0	0	V
Input Voltage	V_{IH}	2.4	—	6.5	V
	V_{IL}	-1.0	—	0.8	V

Note All voltages referenced to V_{SS} .



■ PIN ARRANGEMENT



A0~A7	Address Inputs
CAS	Column Address Strobe
I/O1~I/O4	Data In/Data Out
OE	Output Enable
RAS	Row Address Strobe
WRITE	Read/Write Input
V_{CC}	Power (+5V)
V_{SS}	Ground

■ DC ELECTRICAL CHARACTERISTICS ($T_a=0$ to 70°C , $V_{CC}=5\text{V}\pm 10\%$, $V_{SS}=0\text{V}$)

Parameter	Smbol	HM48416AP-12		HM48416AP-15		HM48416AP-20		Unit	Notes
		min	max	min	max	min	max		
Operating Current ($\overline{\text{RAS}}$, $\overline{\text{CAS}}$ Cycling; $t_{RC}=\text{min}$)	I_{CC1}	—	60	—	55	—	45	mA	1, 2
Standby Current ($\text{RAS}=\overline{V_{IH}}$, Dout=High Impedance)	I_{CC2}	—	3.5	—	3.5	—	3.5	mA	
Refresh Current (RAS Cycling, $\text{CAS}=\overline{V_{IH}}$, $t_{RC}=\text{min}$)	I_{CC3}	—	42	—	38	—	33	mA	2
Standby Current ($\text{RAS}=\overline{V_{IH}}$, Dout Enable)	I_{CC5}	—	5.5	—	5.5	—	5.5	mA	1
Page Mode Current ($\text{RAS}=\overline{V_{IL}}$, CAS Cycling; $t_{PC}=\text{min}$)	I_{CC6}	—	42	—	38	—	33	mA	1, 2
Input Leakage ($0 < V_{in} < 6.5\text{V}$)	I_{LI}	-10	10	-10	10	-10	10	μA	
Output Leakage (Dout is disabled, $0 < V_{out} < 5.5\text{V}$)	I_{LO}	-10	10	-10	10	-10	10	μA	
Output Levels High ($I_{out}=-5\text{mA}$)	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	V	
Output Levels Low ($I_{out}=4.2\text{mA}$)	V_{OL}	0	0.4	0	0.4	0	0.4	V	

Notes) 1. I_{CC} depends on output loading condition when the device is selected, I_{CC} max is specified at the output open condition.

2. Current depends on cycle rate: maximum current is measured at the fastest cycle rate.

■ CAPACITANCE ($V_{CC}=5\text{V}\pm 10\%$, $T_a=25^\circ\text{C}$)

Parameter	Address	Symbol	typ	max	Unit	Notes
Input Capacitance		C_{in1}	—	5	pF	1
	$\overline{\text{RAS}}$, $\overline{\text{CAS}}$, $\overline{\text{WRITE}}$, $\overline{\text{OE}}$	C_{in2}	—	10	pF	1
Output Capacitance	Data In/Data out	$C_{I/O}$	—	10	pF	1, 2

Notes) 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\text{CAS}=\overline{V_{IH}}$ to disable Dout.

■ ELECTRICAL CHARACTERISTICS AND RECOMMENDED AC OPERATING CONDITIONS

($T_a=0$ to 70°C , $V_{CC}=5\text{V}\pm 10\%$, $V_{SS}=0\text{V}$)^{1), 10)}

Parameter	Symbol	HM48416AP-12		HM48416AP-15		HM48416AP-20		Unit	Note
		min	max	min	max	min	max		
Random Read or Write Cycle Time	t_{RC}	230	—	260	—	330	—	ns	
Read-Write Cycle Time	t_{RWC}	320	—	360	—	450	—	ns	
Page Mode Cycle Time	t_{PC}	130	—	145	—	190	—	ns	
Access Time from RAS	t_{RAC}	—	120	—	150	—	200	ns	2, 3
Access Time from $\overline{\text{CAS}}$	t_{CAC}	—	60	—	75	—	100	ns	3, 4
Output Buffer Turn-off Delay referenced to $\overline{\text{CAS}}$	t_{OFF1}	—	35	—	40	—	50	ns	5
Transition Time (Rise and Fall)	t_T	3	35	3	35	3	50	ns	6
RAS Precharge Time	t_{RP}	100	—	100	—	120	—	ns	
RAS Pulse Width	t_{RAS}	120	10000	150	10000	200	10000	ns	
$\overline{\text{CAS}}$ Pulse Width	t_{CAS}	60	10000	75	10000	100	10000	ns	
RAS to $\overline{\text{CAS}}$ Delay Time	t_{RCD}	25	60	25	75	30	100	ns	7
RAS Hold Time	t_{RSH}	60	—	75	—	100	—	ns	
$\overline{\text{CAS}}$ Hold Time	t_{CSH}	120	—	150	—	200	—	ns	
$\overline{\text{CAS}}$ to RAS Precharge Time	t_{CRP}	-10	—	-10	—	-10	—	ns	
Row Address Set-up Time	t_{ASR}	0	—	0	—	0	—	ns	
Row Address Hold Time	t_{RAH}	15	—	15	—	20	—	ns	
Column Address Set-up Time	t_{ASC}	0	—	0	—	0	—	ns	
Column Address Hold Time	t_{CAH}	20	—	25	—	30	—	ns	
Column Address Hold Time referenced to RAS	t_{AR}	80	—	100	—	130	—	ns	
Write Command Set-up Time	t_{WCS}	0	—	0	—	0	—	ns	8
Write Command Hold Time	t_{WCH}	40	—	45	—	55	—	ns	

(to be continued)

Parameter	Symbol	HM48416AP-12		HM48416AP-15		HM48416AP-20		Unit	Note
		min	max	min	max	min	max		
Write Command Hold Time referenced to RAS	t_{WCR}	100	—	120	—	155	—	ns	
Write Command Pulse Width	t_{WP}	40	—	45	—	55	—	ns	
Write Command to RAS Lead Time	t_{RWL}	40	—	45	—	55	—	ns	
Write Command to CAS Lead Time	t_{CWL}	40	—	45	—	55	—	ns	
Data-in Set-up Time	t_{DS}	0	—	0	—	0	—	ns	9
Data-in Hold Time	t_{DH}	40	—	45	—	55	—	ns	9
Data-in Hold Time referenced to RAS	t_{DHR}	100	—	120	—	155	—	ns	
Read Command Set-up Time	t_{RCS}	0	—	0	—	0	—	ns	
Read Command Hold Time referenced to CAS	t_{RCH}	0	—	0	—	0	—	ns	
Read Command Hold Time referenced to RAS	t_{RRH}	10	—	10	—	10	—	ns	
Refresh Period	t_{REF}	—	2	—	2	—	2	ms	
CAS to WE Delay Time	t_{CWD}	105	—	125	—	160	—	ns	8
RAS to WE Delay Time	t_{RWD}	165	—	200	—	260	—	ns	8
CAS Precharge Time (for Page-mode Cycle Only)	t_{CP}	60	—	60	—	80	—	ns	
CAS Precharge Time	t_{CPN}	35	—	40	—	50	—	ns	
RAS Precharge to CAS Hold Time	t_{RPC}	0	—	0	—	0	—	ns	
Access Time from OE	t_{OAC}	—	35	—	40	—	50	ns	3
Output Buffer Turn-off Delay referenced to OE	t_{OFF2}	—	35	—	40	—	50	ns	5
OE to Data-in Delay Time	t_{ODD}	35	—	40	—	50	—	ns	11
OE Hold Time referenced to CAS	t_{OCH}	0	—	0	—	0	—	ns	

Notes:

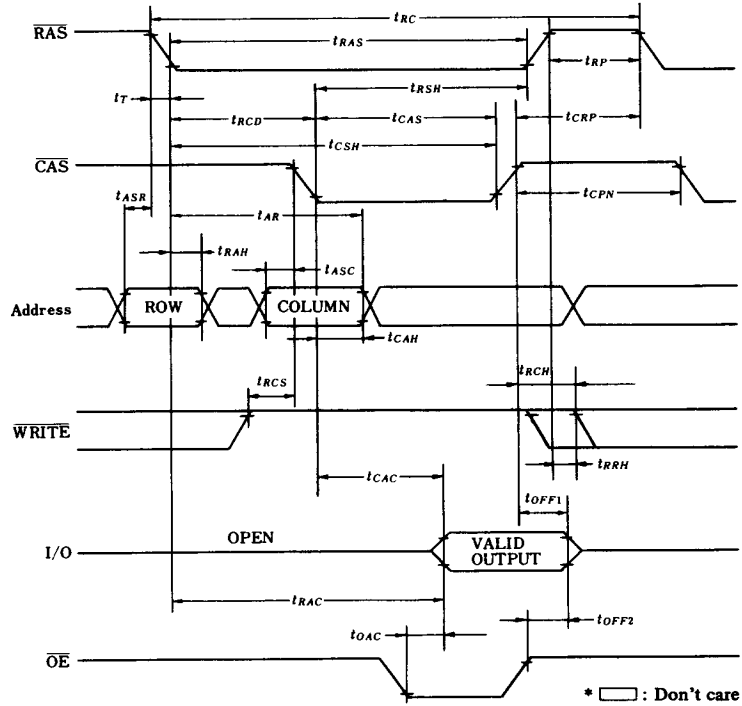
1. AC measurements assume $t_T = 5\text{ns}$.
2. Assumes that $t_{RCD} \leq t_{RCD}(\text{max})$. If t_{RCD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
3. Measured with a load circuit equivalent to 2TTL loads and 100pF.
4. Assumes that $t_{RCD} \geq t_{RCD}(\text{max})$.
5. $t_{OFF1}(\text{max})$ and $t_{OFF2}(\text{max})$ define the time at which the output achieves the open circuit condition.
6. $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL} .
7. Operation within the $t_{RCD}(\text{max})$ limit insures that $t_{RAC}(\text{max})$ can be met, $t_{RCD}(\text{max})$ is specified as a reference point only; if t_{RCD} is greater than the specified $t_{RCD}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
8. t_{WCS} , t_{CWD} and t_{RWD} are not restrictive operating parameters.

They are included in the data sheet as electrical characteristics only; if $t_{WCS} \geq t_{WCS}(\text{min})$, the cycle is an early write cycle and the data output pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{CWD} \geq t_{CWD}(\text{min})$ and $t_{RWD} \geq t_{RWD}(\text{min})$ the cycle is a read-write cycle and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.

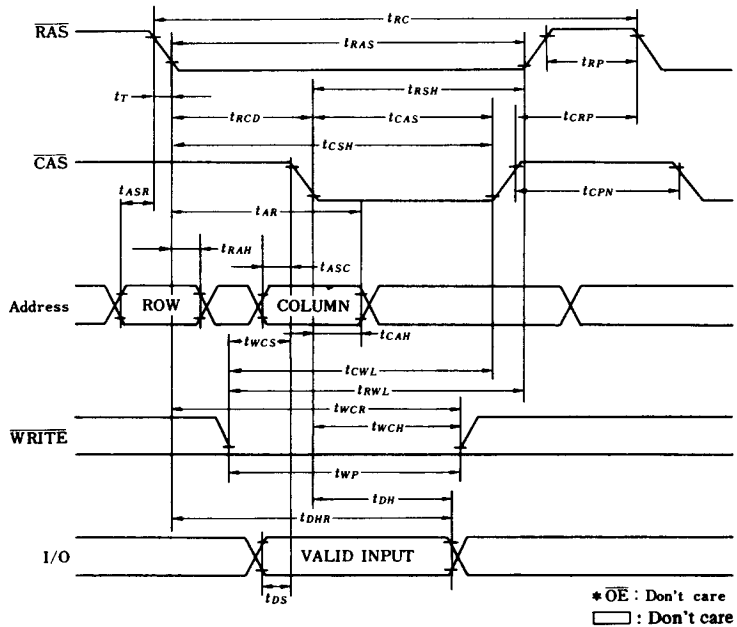
9. These parameters are referenced to CAS leading edge in early write cycles and to WE leading edge in delayed write or read-modify-write cycles.
10. An initial pause of 100 μs is required after power-up followed by a minimum of 8 initialization cycles.
11. In delayed write or read-modify-write cycles, OE must disable output buffers prior to applying data to the device.

■ TIMING WAVEFORMS

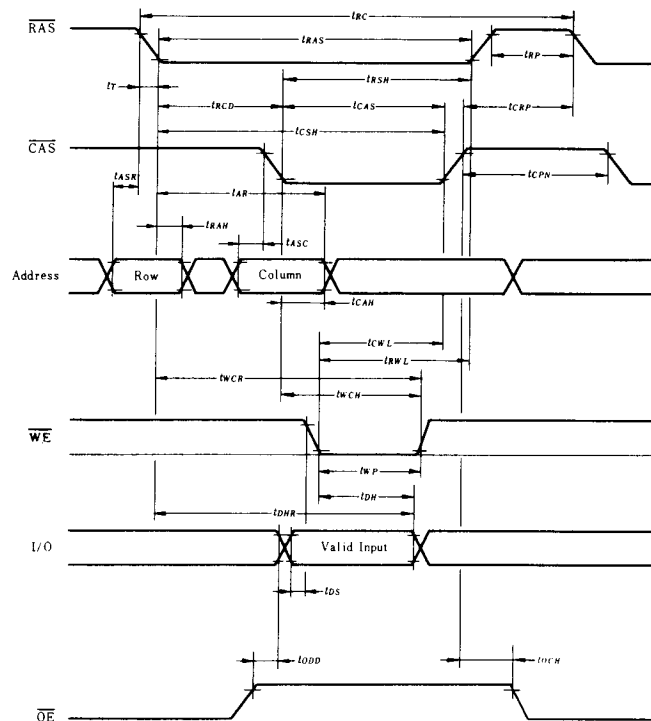
● Read Cycle



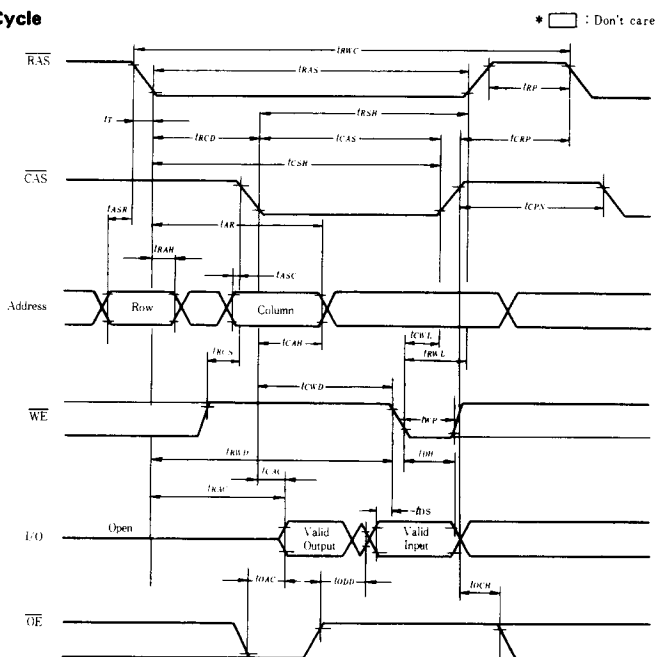
● Early Write Cycle



● Delayed Write Cycle



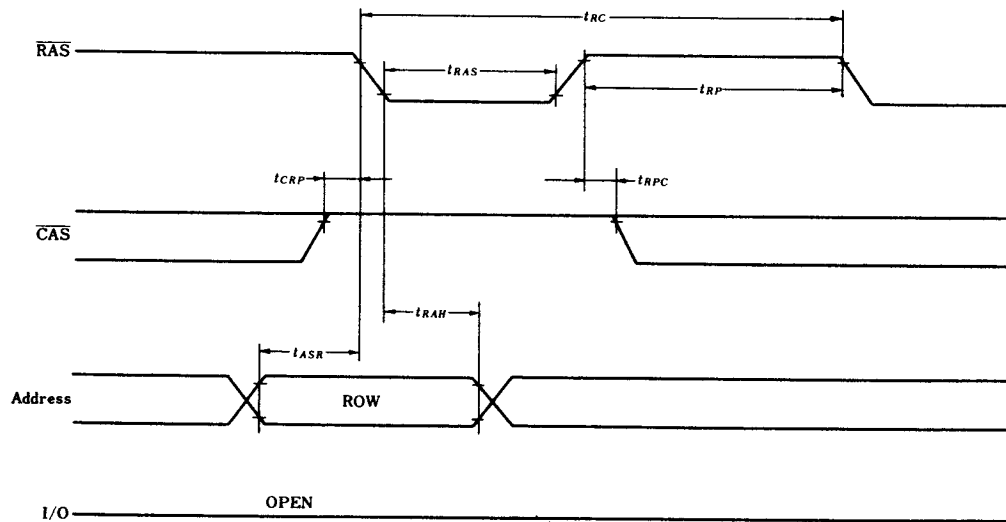
● Read Modify Write Cycle



* □ : Don't care

* □ : Don't care

• **RAS Only Refresh Cycle**



*OE, WE: Don't care
 □: Don't care